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Revision A

Prepared by SEM/CCMVALE Afrah Sadiq + 46 10 80 12250 Contents responsible if other than preparer

Document number CCDA09:482 Date 2009-09-02 Remarks

Approved by

SEM/CCMVALE Peter Lindeborg + 46 10 80 24 368

Receiver: Federal Communication Commission and Certification and Engineering Bureau Industry Canada

Application FFC ID: PY7A3880046,

IC: 4170B-A3880046

Type number: AAD-3880046-BV

Statement of Hardware Change

Valid for: Permissive Change Class II on Hardware-B for AAD-3880046-BV

Hardware-B changes:

The SIM card holder has been replaced to improve the communication link between control circuit's on the main PCB and the SIM card.

These changes do not affect Bluetooth performance. The Bluetooth test report (report no. 1-1065-33-04/09, dated 2009-06-25) apply for Hardware-B

Best Regards,

Peter Lindeborg

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Approved Checked Date Rev Reference

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2009-07-14 A

HW change description for

MS type:	AAD-3880046-BV	AAD-3880047-BV
Supporting:	GSM 850/900/1800/1900	GSM 850/900/1800/1900
	FDD I/VIII	FDD I/II/V
Market name:	Yari, U100i	Yari, U100a
FCC id:	PY7A3880046	PY7A3880047
IC id:	4170B-A3880046	4170B-A3880047
Hardware:	A to B	A to B

1 Background

The following changes have been done between HW A and B for MS type AAD-3880046-BV and AAD-3880047-BV:

- Filter has changed value to improve performance for Fast transient.
 - Component Z2400 changed to Sony Ericsson part number 1225-1423
- 2 Inductors added to improve Current Clamp performance. Sony Ericsson part number 1000-2609
- Conducted gasket added between Combi Flex and hinge to improve RSE performance.
- Increased ground plane on Combi Flex to reduce SAR level.
- Improved SIM lid (added connection via screw to ground plane)
- Changed mechanics for the SIM interface. (SIM lid is new and base carrier is changed so that SIM card is inserted from the side.)



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Α

Re-testing consequences 2

2.1 **Conducted re-testing**

2.1.1 3GPP TS 51.010 Requirement

TC	Name
27.11.x and 27.17.x	SIM electrical and logical

ETSI TS 102 230

TC	Name
5.x, 6.x, 7.x and 8x	SIM electrical and logical

2.2 Radiated and EMC testing

- FCC Part 22/24 Radiated Power
- FCC Part 22/24 Radiated Emission
- FCC Part 22/24 Conductive Output Power
- OTA (Over The Air) in all bands
- 12.2.1 Radiated spurious emissions MS allocated a channel
- 12.2.2 Radiated spurious emissions MS in idle mod
- **ESD**